JSAP EXPO Spring 2026

Ookayama Campus,
Institute of Science Tokyo

March 15(Sun.)-18(Wed.)

Exhibition & Sponsorships Opportunities

The 73rd JSAP Spring Meeting 2026
Dates: March 15(Sun.)- 18(Wed.), 2026
Venue: Ookayama Campus, Institute of Science Tokyo

Sponsored by The Japan Society of Applied Physics
Operational Management by Nikkan Kogyo Communications, Inc.

Message from President

President's Message

We sincerely appreciate your continued support for the activities of the Japan Society of Applied Physics.

We are pleased to announce that The 73rd JSAP Spring Meeting will be held as a hybrid event, combining on-site and online formats, at Ookayama Campus of Institute of Science Tokyo, from March 15(Sun.) to March 18(Wed.), 2026.

This Meeting is one of the largest academic conferences in the field of applied physics, bringing together approximately 12,000 researchers and engineers from universities, public research institutions, and industry. The program features around 3,500 cutting-edge presentations, providing an exceptional forum for academic exchange and industry–academia collaboration.

The accompanying exhibition, "JSAP EXPO Spring 2026," is an integral part of the conference. The exhibition venue also hosts the official poster session, attracting a large number of conference participants throughout the event. The exhibition is highly regarded as a valuable venue for companies to showcase their latest products, technologies, and services, as well as to engage in information exchange and networking with researchers and engineers.

In addition, the poster session held in the exhibition hall includes presentations by outstanding students from across Japan, offering participating companies a unique opportunity to interact directly with young talent and support the development of the next generation of researchers.

The Japan Society of Applied Physics remains committed to enhancing opportunities for in-person interaction and increasing on-site participation. We sincerely invite you to support JSAP EXPO Spring 2026 as a sponsor and to take advantage of this outstanding opportunity to strengthen your presence within the applied physics community.

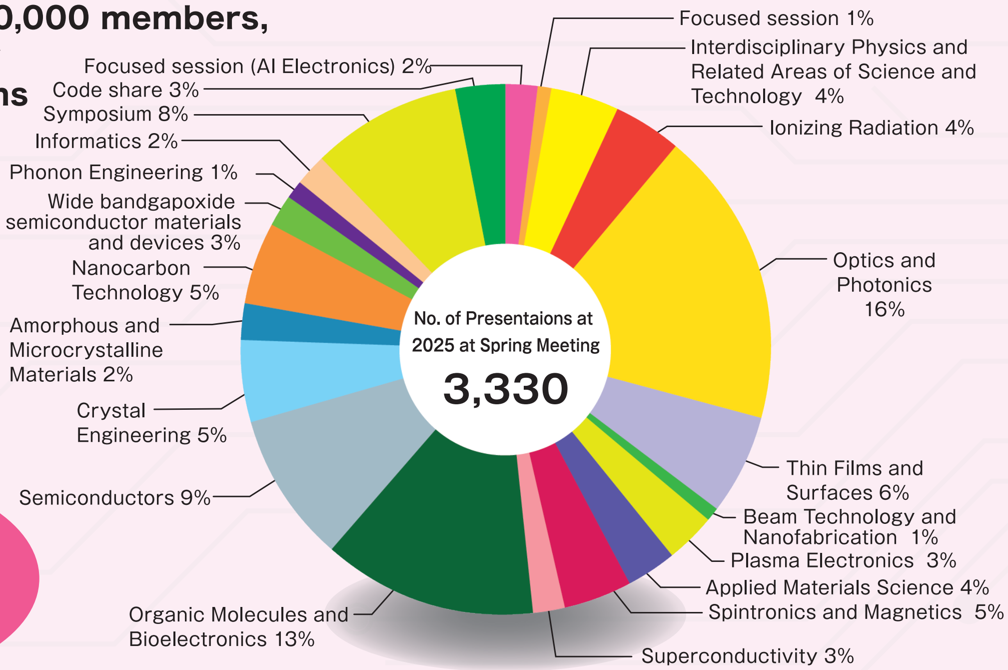
President, The Japan Society of Applied Physics

Tsunenobu Kimoto

Professor, Kyoto University

About JSAP

JSAP has nearly 20,000 members, and approximately 3,500 presentations on the latest research are given at every JSAP annual meeting.

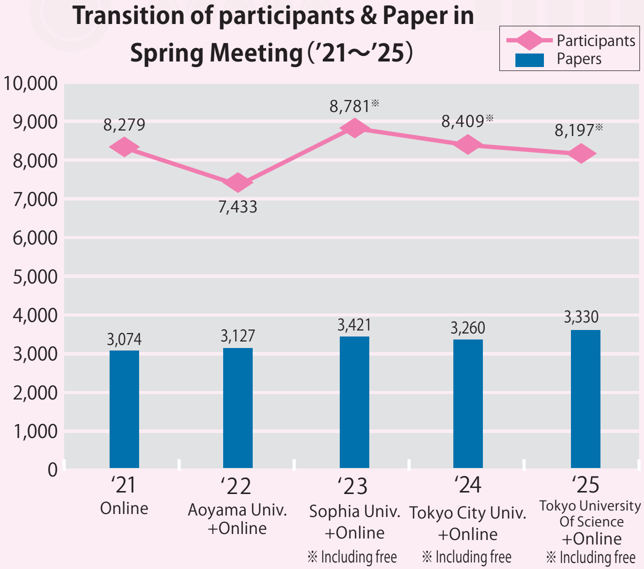


The number of participants from industry is steadily increasing.

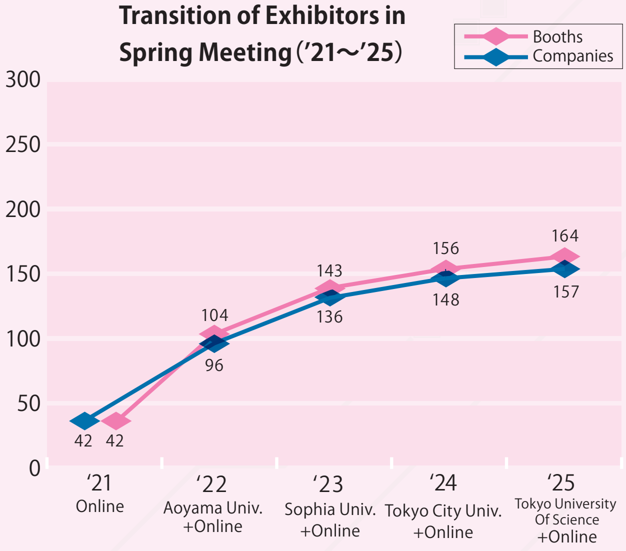
(Spring'25: 1,665 participants)

About JSAP Spring Meeting & EXPO

Transition of participants & Paper in Spring Meeting ('21～'25)



Transition of Exhibitors in Spring Meeting ('21～'25)



About JSAP EXPO

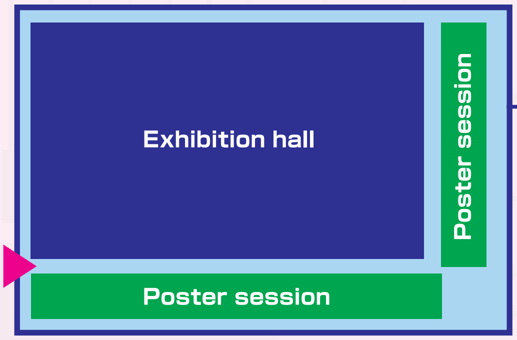
Application DEADLINE January 30 (Fri.), 2026

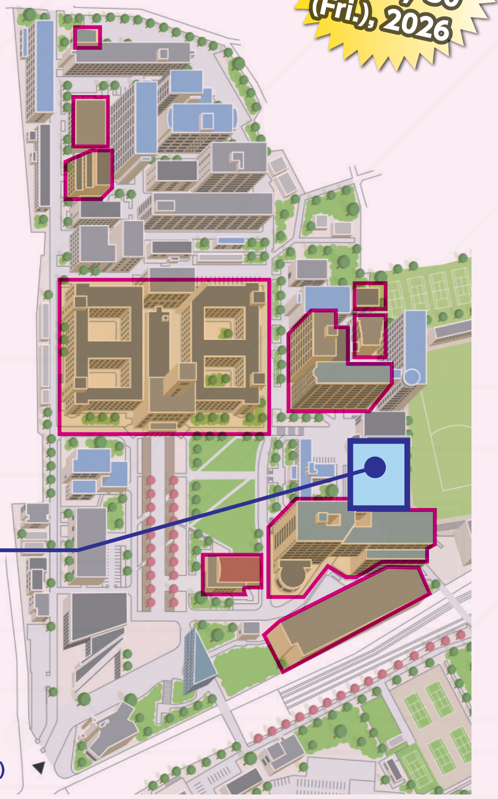
Venue: Gymnasium, Ookayama Campus, Institute of Science Tokyo
2-12-1 Ookayama, Meguro-ku, Tokyo 152-8550, Japan

Dates: March 15(Sun.) – March 17(Tue.), 2026: 9:30am – 6:00pm, 18(Wed.), 2026: 9:30am – 1:00pm
Move-in & Installation: March 14(Sun.): 2:00pm – 7:00pm / 15 (Mon.): 8:30am – 9:30am
Dismantling & Move-out: March 18(Wed.): 1:00pm – 3:00pm

Exhibition Layout

The exhibition will be held on the first floor of the gymnasium.
The same floor will feature:
• Drink corner / Lounge / Lottery corner / Poster Sessions
Poster sessions will take place on both the exhibition floor (1F) and the martial arts hall (B1F), ensuring high visitor traffic throughout the exhibition.





Indoor gymnasium
- ✓ Exhibition
- ✓ Drinks Corner
- ✓ Lounge
- ✓ Raffle Corner
- ✓ Poster Session (1F, B1F)

(image of layout)

Exhibition fee

(excluding tax) (Please transfer the exhibition fee, including options, to the designated account by Friday, February 27, 2026)

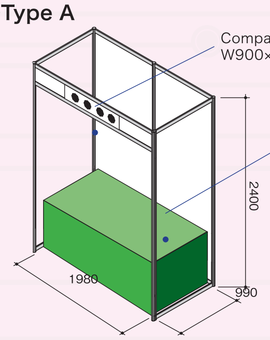
Type A (Standard Booth)
- ･JSAP Corporate Members / Advertiser of JSAP Membership Journal “OYO BUTURI”: 250,000JPY
- ･Standard: 270,000JPY

Type B (Enhanced Booth)
- ･JSAP Corporate Members / Advertiser of JSAP Membership Journal “OYO BUTURI”: 280,000JPY
- ･Standard: 300,000JPY

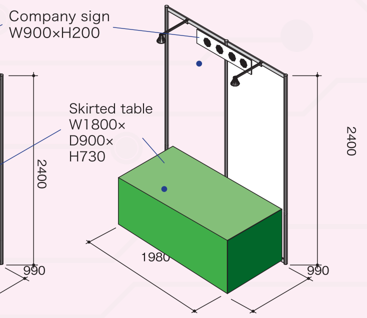
Books Publishers: 150,000JPY

Career & Recruitment Exhibits: Please select either Type A or Type B above.

◎Type A



◎Publisher Booth



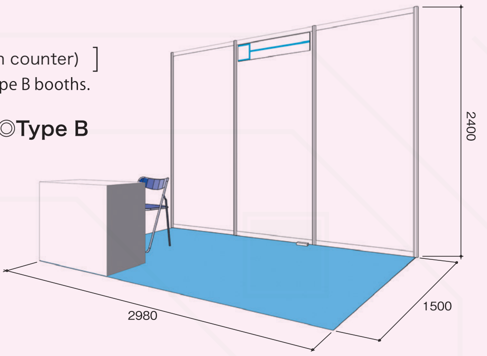
Booths Specifications

Type A Booth W1980 × D990 × H2400
[includes; company sign, back and side wall (no side wall for the corner booths.), 1 display table (W1800 X D900 X H730), 1 chair, 1 lighting (40W)]

Type B Booth (Limited to 20 booths) W2980 × D1500 × H2400
[includes; Company sign, back and side wall, carpet, exhibition stand (or reception counter)]
*You can also select an exhibition stand (W1200 x D600 x H730mm) for both Type A and Type B booths.

Publisher Booth W1980 × D990 × H2400
[includes; company sign, back panel, display stand (W1800 x D900 x H730) Chair x 1, Spotlight x 2.), 1 display table (W1800 X D900 X H730), 1 chair.]

◎Type B



Catchphrase
Please provide a concise catchphrase (approximately 20 characters) that clearly and effectively conveys your exhibition content to visitors.

Optional Selection Items and Pricing

Power supply and electricity charges (AC single phase 100V 50Hz)

※ Electricity charges include mains installation costs.
※ If you require 200V single-phase or three-phase, separate power installation work will be required, which will be more expensive.

1W- 500W	10,000 JPY	501W- 1000W	15,000 JPY
1001W- 2000W	25,000 JPY	2001W- 3000W	35,000 JPY

Below that, an additional 10,000 yen will be added for every 1000W.

If you order additional electricity, you need to order additional electrical outlets.

2 Electrical Outlets (750W) *including wiring	**3,500JPY**
Other Options (Consult if you need unlisted options.)	
LED Spotlights *including electrical wiring	**4,500JPY**
Brochure Stand (12 holders)	**7,500JPY**

JSAP EXPO Spring 2025 & Autumn 2025 Exhibitors List

AA Portable Power Corporation
Academeia Co., Ltd.
AD Science Inc.
Advanced Research Infrastructure for Materials and Nanotechnology in Japan(ARIM Japan)
AdvanceSoft Corporation
AIST Nano-Processing Facility
Aixtal Corporation
ALD Japan, Inc.
Alnair Corporation
ALS Technology Co., Ltd.
APOLLOWAVE Corporation
APROLINK
ARISE TECHNOLOGY Co., Ltd.
ARMSSYSTEM Co., Ltd.
Artner Co., Ltd.
ASKindex Co., Ltd.
Astellatech, Inc.
Autex Inc.
AXIS Corporation
BENEQ KK
Bluefors K.K.
Bruker Japan K.K.
Bunkoukeiki Co., Ltd.
CHUO PRECISION INDUSTRIAL CO., LTD.
Coherent Japan Inc.
Communication by chip-scale combs
Coop-J Consortium
CORNES Technologies Ltd.
COSMOTEC Corporation
Crosslight Software Inc. Japan Branch
Crystal Base Co., Ltd.
Crystal Systems Corporation
Cybernet Systems Co., Ltd.
DAIWA TETSUGEN KOHSAN CO., LTD
DIAVAC LIMITED
E&E evolution Co., Ltd.
EBA JAPAN CO., LTD.
Edwards Japan Ltd.
EIKO ENGINEERING/ EIKO CORPORATION
ELIONIX INC.
Emerging Technologies Corporation
EpiQuest, Inc.
ESCO, Ltd.
Eurofins EAG Materials Science Tokyo Corporation
Evident Corporation
Expp Co., Ltd.
Flexcompute
Found Four Co., Ltd.
FUJIFILM Business Innovation Corp.
Fujikin Incorporated
Fujitsu Limited
Fukui Prefecture Tourism Federation
Fukuoka Industry, Science & Technology Foundation
FULL-TECH CO., LTD
Furuuchi Chemical Corporation
Furuya Metal Co., Ltd.
Gaianixx Inc.
GIFU CONVENTION AND VISITORS BUREAU
Hakuto Co., Ltd.
Hamamatsu & Lake Hamana Tourism Bureau
HAMAMATSU PHOTONICS K.K.
Hanwa Trading Corporation
Heidelberg Instruments KK
Hightec Systems Corporation
Himeji Convention & Visitors Bureau
HiSOL, Inc.
HTL Co. Japan Ltd.
Hundred Semiconductors Inc.
IKEDA SCIENTIFIC Co., Ltd.
INCUBATION ALLIANCE, INC.
Innovation Science Co., Ltd.
Ion Technology Center Co., Ltd.
IOP Publishing
IRC Inc.
ISHIHARA CHEMICAL CO., LTD.
IWATSU ELECTRIC CO., LTD.
J.A.Woollam Japan Corporation
JAPAN HIGH TECH CO., LTD.
Japan Laser Corporation
Japan Synchrotron Radiation Research Instutute
JASCO Corporation
JNC Petrochemical Corporation
JRR-3@JAEA
JSW AFTY Corporation
K&R Creation Co., Ltd.
Kagawa Prefecture MICE Promotion Council.
KANTO CHEMICAL CO., INC.
Kashiyama Industries, Ltd.
Katsura Opto Systems Co., LTD
KEISOKU ENGINEERING SYSTEM CO., LTD.
Kenix Corporation
Keystone International Co., Ltd.
Keystone Scientific K.K.
Kinokuniya Company Ltd.
KLA Corporation
Kogakugiken Corp.
Kojundo Chemical Laboratory Co., Ltd.
KOKUSAI ELECTRIC CORPORATION
Koozyt, Inc.
Kosaka Laboratory Ltd.
Kumamoto City
Lasertec Corporation
LightBridge Ltd.
LightStone Corp.
Malvern Panalytical division of Spectris Co., Ltd
Matsue Convention Bureau Kunibiki Messe
MDPI Japan G.K.
Menlo Systems K.K.
MICROJET Corporation
Micron Inc.
MICRONICS JAPAN Co., LTD.
MIRISE Technologies Corporation
MITSUBISHI GAS CHEMICAL NEXT COMPANY, INC.
MIYAZAKI PREFECTURE TOURISM ASSOCIATION
MO sangyo Co., LTD.
MSH Systems, Inc.
Mutsumi Corporation
NAGOYA CONVENTION & VISITORS BUREAU
Nakamura Scientific Instruments Industry Co., Ltd.
NanoAndMore Japan K.K.
NanoMagnetics Instruments Ltd., UK
Nanophoton - a Bruker Company
Nara Institute of Science and Technology
National Institute of Advanced Industrial Science and Technology (AIST)
NEOARK CORPORATION
NextLab Inc.
Nextron Corporation
NIHON DENSHI SEIKI CO., LTD.
NIHON KOSHUHA CO., LTD.
NIKI GLASS CO., LTD.
NIPPON STEEL TECHNOLOGY Co., Ltd.
NIPPON TELEGRAPH AND TELEPHONE CORPORATION
NISSAN ARC, LTD.
Nissin Kikai Co., Ltd.
NPS Co., Ltd.
NTK International Corporation
NTT, Inc.
OHTAMA CO., LTD.
Okinawa Convention & Visitors Bureau
OMRON Corporation
Opto Science, Inc.
OPTOQUEST CO., LTD./ DYNET CORPORATION
OptoSirius Corporation
OptQC Corp.
OSAKA VACUUM, LTD.
Oxford Instruments KK
OXIDE Corporation
Park Systems Japan Inc.
PASCAL CO., LTD.
Phisix Technology Inc.
PHOTOTECHNICA Corp.
Piezo Parts Co., Ltd.
PNEUM Co., Ltd.
Preferred Computational Chemistry, Inc.
Priways Co., Ltd.
Pulstec Industrial Co., Ltd.
QD Laser, Inc.
Quantum Design Japan, Inc.
Quemix Inc.
RAD DEVCE CO., LTD.
R-DEC Co., Ltd.
Renishaw K.K.
Research Support HR Bank Inc.
RICHMORE INTERNATIONAL, CORP.
Rigaku Corporation
RIGOL JAPAN CO., LTD.
SAES Getters S.p.A.
Sagami Chemical Research Institute
SAKURA COLOR PRODUCTS CORPORATION
SAN-EI ELECTRIC CO., LTD.
Sanoh Industrial Co., Ltd.
santec
SANYU ELECTRON CO., LTD
ScienceEdge Inc.
Scienta Omicron, Inc.
SDI Company Ltd.
Semilab Japan KK
SHIMADZU CORPORATION
SHINKOSHA CO., LTD.
SIJTechnology, Inc.
SK Fine CO., LTD.
Spectra Design Ltd.
SPLEAD Corporation
Springer Nature Japan K.K.
STR Japan K.K.
STRATEGIC Corporation
SUGA Co., Ltd.
SURUGA SEIKI Co., Ltd.
Suzuki Shokan Co., Ltd.
SYSTEMHOUSE SUNRISE Inc.
T.E.M. Incorporated
TANAKA Precious Metal Technologies Co., Ltd.
Techno Print Co., Ltd.
TEGA Science, Inc.
TEGARA Corporation
Tektronix
Teledyne Japan Corporation
THAMWAY CO., LTD
The OYAMA Company, LTD.
THERMO RIKO CO., LTD.
THINKY CORPORATION
Thorlabs Japan Inc.
TNS Systems LLC/ Priways Co., Ltd./ TPT Japan Co., Ltd.
Toko Instruments, Inc.
Tokyo Chemical Industry Co., Ltd.
TOKYO ELECTRONICS CO., LTD.
Tokyo Instruments, Inc.
Tokyo Printing Ink
TOMOE ENGINEERING Co., Ltd
Toray Precision Co., Ltd.
Toray Research Center, Inc.
Toshiba Nanoanalysis Corporation
Tosoh Corporation
TOYAMA CO., LTD.
Toyama Convention Bureau
TOYO Corporation
TOYO PRECISION PARTS MFG. CO., LTD
Toyota Technological Institute
ULVAC TECHNO, Ltd/ ULVAC EQUIPMENT SALES, Inc.
ULVAC-PHI, INCORPORATED./ HORIBA TECHNO SERVICE CO., LTD.
UNISOKU Co., Ltd.
USACO Corporation
Utsunomiya Convention & Visitors Bureau
VACUUM PRODUCTS Co., Ltd.
VISTA Corporation
Visualix, K.K
YAKO SANGYO Co., Ltd.
Yokogawa Test & Measurement Corporation
Zurich Instruments AG

Symposium Sponsorship Prospectus

Deadline: February 10, 2026 (Tuesday)

You can sponsor the "Symposium" to be held during the conference. We plan symposiums on themes that capture the latest trends in various fields of applied physics. This allows you to promote your research to symposium participants who are keen on cutting-edge research.

Fee		Benefits
Platinum	200,000 JPY *1Limited to one company per symposium	(1) Seminars on equipment and technology (10 minutes) can be held after the session. (2) Free registration per one person for the 73rd JSAP Spring Meeting 2026 (3) Logo on the symposium page of the web program (Link can be set) (4) Logo on the symposium page of the conference website (Link can be set) (5) Place flyers at symposium room(only during the symposium) or advertized to conference website on symposium.
Gold	100,000 JPY	(1) Logo on the symposium page of the web program (URL links can be set) (2) Logo on the symposium page of the conference website (URL links can be set) (3) Place flyers at symposium room(only during the symposium) or advertized to conference website on symposium.

Date	Scheduled time	No.	Symposium Title
Public Symposium			
March 15 (Sun.)	13:30-17:30	NT2	How can we achieve D&I with international diversity in academia and industry in the field of applied physics?
March 16 (Mon.)	13:30-17:00	NT1	Attention Job Seeking Students! Exploring the Fusion of AI and Semiconductors: Scientific Insights and Engineering Challenges
March 17 (Tue.)	13:30-17:00	NT3	Can semiconductor technology improve well-being?
	13:30-18:00	T22	From Space Development to Space Industry: Insights for Business Entry and the Latest Technological Trends
Symposium			
March 15 (Sun.)	13:30-17:30	T3	Opening the Future of Decommissioning with Radiation Measurement Technologies: Challenges and Progress at Fukushima Daiichi Nuclear Power Station
	10:00-17:00	T4	Frontiers and Perspectives on Fault-Tolerant Quantum Computing
	13:30-18:00	T5	Chirality in Optics : Fundamentals and Innovative Technologies
	9:00-18:30	T13	Atomic Layer Process (ALP) analysis and application technologies (3)
	13:30-18:30	T16	Application of informatics technology in the field of nanobiotechnology
	13:30-17:30	T17	Cutting edge nanotechnology for bio-sensor & 2D materials -Realization of a pandemic-free society with graphene FET sensors capable of rapid detection of human infectious viruses-
	13:30-17:35	T19	Bridging the Gap: Computational Approaches to Address Challenges in Photoelectronic Organic Devices at the Physical-Cyberspace
	13:30-18:00	T20	Advances in Energy Conversion Research through Photoactive Materials and Interface Engineering
March 16 (Mon.)	13:30-18:30	T1	Lab to Fab 2: Bridging Semiconductor Research with Scalable and Sustainable Manufacturing
	13:30-17:30	T2	Human Resource Development and Technology Transfer in Business and Education: Current Status and Future Outlook
	13:30-18:00	T6	Metasurfaces Close to Practical Realization
	13:30-17:50	T7	Innovation in Physical Chemistry and Quantum Life Sciences via Photothermal Conversion
	13:30-16:30	T8	Visualization of social infrastructure and disaster prevention using distributed acoustic sensors (DAS)
	13:30-18:00	T12	Plasma-induced Plant Responses
	13:30-18:30	T14	Next-Generation Biomedical Applications: Pioneered by Magneto-Science and Medical-Engineering Integration
	13:30-17:00	T21	New Developments in Microfabrication and MEMS Technologies Pioneering Next-Generation Sensing and Communications
	10:00-18:30	T24	AI × Robotics × Human: Opening New Frontiers in Autonomous Materials Research
March 17 (Tue.)	13:30-17:45	T10	Frontiers of Semiconductor Characterization Techniques
	13:30-18:00	T11	Next-generation electron sources and new developments in electron beam technology
	13:30-18:00	T15	The Prospects of Data Storage and Non-Volatile Memory Technologies in the AI era
	13:30-18:30	T18	Neuromorphic computing at the convergence of biology, electronics, and photonics
	13:30-17:00	T23	New Frontiers in Non-equilibrium Materials Unlocked by Spacetime Commutativity
March 18 (Wed.)	13:30-17:05	T9	Emerging research trends in thin-film materials, devices, and processes for future technological innovation

Luncheon Seminar

Luncheon Seminar Prospectus

40 minutes luncheon seminars at the session room during the lunch time.

Application DEADLINE January 30 (Fri.), 2026

Scenes from Luncheon Seminars (Spring meeting 2019)

Dates and Hours: Seminar Contents

Dates and Hours: March 15(Sun.)-18(Wed.), 2026
* Lunch time varies by session

Sponsors can decide the contents of the seminar.

e.g.) Company PR(40 min.)
Invited speaker (30 min.)+ Company' s products and technology lecture(10 min.)

※Please note that the venue is limited. We will accept applications on a first-come, first-served basis (limited to 5 slots per day). Please note that we may not be able to accommodate all requests.

※Please follow the rules of the luncheon strictly. If you wish to change the regulations, please contact us. We will make a decision on whether or not to hold the event after consultation.

Fees

*The cost for lunch boxes in not included.

Room Capacity		100 people	50 people
Exhibitors	Standard	160,000JPY	124,000JPY
	JSAP Corporate Members	140,000JPY	104,000JPY
Non-Exhibitors	Standard	230,000JPY	194,000JPY
	JSAP Corporate Members	210,000JPY	174,000JPY

Benefits

◉Free registration per one person
◉Provision of seminar participant data

Luncheon seminar flyers will be published on all ofthe below.

①Official Website

②X(@jsapexpo)

③Conferecne Web Program

④Official guide book

After application

- ・End of January: Luncheon venue and time to be decided
- ・February 6: Guidebook (vertical, monochrome) and website
- ・Mid to late February: Lunch box application

Advance registration will be accepted on the lecture website. If there are seats available, registration will be accepted at the venue on the day.

Short Seminar

Short Seminar

Application DEADLINE January 30 (Fri.), 2026

Short seminars can be held for attendees after your desired oral session (excluding symposiums). In addition to introducing products, technologies, and services, these seminars are also suitable for recruiting as they can be targeted.

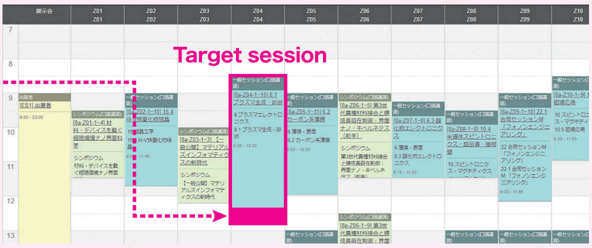
Dates and Hours: Seminar Contents

Dates and Hours : March 15(Sun.)-18(Wed.), 2026 Hours: After the Oral Session
How to hold it: Session venue
Presentation: On-site

Event fee (excluding tax)	Presentation Time	Participant Data	Benefits	Recording & Delivered	Exhibitors/ JSAP Corporate Member	Satandard
Short seminar	10 min.	×	×	×	50,000JPY	80,000JPY

Features of the short seminar

You can select your desired classification and hold (present) your presentation after the relevant session has finished. This will be held in a venue where there are still attendees, making it ideal for PR.
*We may not be able to accommodate your request. We appreciate your understanding.
*You cannot select the symposium. Please apply through a symposium sponsor.



Session Room Sponsorship Prospectus

One company or organization per venue is exclusively allowed to broadcast advertisements (for products, technologies, services, international conferences, and symposiums) within the venue. During breaks and lunch, advertisements will be displayed on the venue screen along with general notices for the conference. In addition to displaying posters inside and outside the venue, you are also free to use the catalog stand outside the venue.

Application DEADLINE February 20 (Fri.), 2026

Novelty items can also be distributed.

Dates and Hours

Dates: March 15(SUN.)-18(Wed.), 2026
Hours: 9:00am-6:00pm
*The start and end time varies by session
*The rest breaks are 15-30 minutes long (One in the morning, one in the afternoon) and lunch break is 60-90 minutes long.

Fee

Exhibitors/ JSAP Corporate Member/ Advertiser of JSAP Membership Journal	1 Room (4 days)	100,000JPY
Satandard	1 Room (4 days)	150,000JPY

スケジュール

Conference Program Open: Early Feb. — Conference program will be posted on the official website

▼

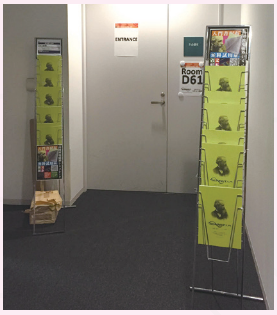
Application Deadline: Feb. 20(Fri.) — Session schedule by room will be sent in early Feb.

▼

Wallpaper Data Submission Deadline: Feb. 24(Tue.) — Please submit a wallpaper data to the secretariat.
* Specifications will be announced after the application.

当日運営

- Please send any catalogs (flyers), posters, etc. to be displayed to us by Friday, March 6, 2026, or deliver them to the designated location on-site the day before the event (Saturday, March 14).
- Two catalog stands will be set up near the entrance to the venue. The secretariat will be responsible for placing catalogs (flyers) on the stands.
- Sales activities (such as having staff on-site) at the venue are not permitted outside the exhibition venue.



Image

広告

Application DEADLINE January 30 (Fri.), 2026

Official Guidebook

The circulation is approximately 17,000 copies! It will be enclosed with the March issue of the journal and also distributed at the venue @ Ookayama Campus, institute of science Tokyo.

Contents

- Conference program
- Events information

General information

- **Circulation : 17,000(JSAP members)**
- **Date of issue : Mar 10(Tue.), 2026**
- **Application deadline : Jun 30(Fri.), 2026**
- **Manuscript deadline : February 10(Tue.), 2026**

Fee

Space & Color	Exhibitor / JSAP Corporate Member Advertiser of JSAP membership Journal	Standard
Back 4 cover	330,000JPY	350,000JPY
Inside 4 cover	270,000JPY	280,000JPY
Inside back 4 cover	240,000JPY	250,000JPY
Front page 4 color	250,000JPY	260,000JPY
Front page B&W	125,000JPY	135,000JPY
Back page B&W	105,000JPY	115,000JPY
only to 2 space 1/2Page Horizontal	90,000JPY	100,000JPY
only to 2 space 1/3Page Horizontal	70,000JPY	80,000JPY

＋ Both formats of Macintosh and Windows, text display data, outlined text data, image and PDF files are desirable.
＋ Image file types: EPS file is best possible, and TIFF, JPEG, GIF are acceptable.
＋ Resolution: 350 dpi or over
＋ Process colors: Cyan, Magenta, Yellow, Black Process colors:*RGB method (Red, Green, Blue) is unacceptable.

Career (Recruitment) ads wanted!!

Would you like to promote your company/ organization through the official guidebook and Oyobuturi(JSAP Issue)? You can convey your strengths and attractions firmly in an article style. Please contact us for details.

Web Contents

Banner ads on JSAP Spring Meeting 2026 website

You can post banner ads on the necessities for participants, official website, web program and applications. It can be used for various announcements such as product and service introductions, information about your company's seminars, directing to video content, and inviting submissions and participation in international conferences.

Official Website

Web Program

Location	Size (pixel)	Display formats	Fee		Duration	The number of places	Application Deadline
			Exhiibitor/JSAP Corporate Memeber	Standard			
1.Official Website							
Top page	W280 x H100	fixed	150,000JPY	200,000JPY	※	8	Feb. 20(Fri.), 2026
2.Web Program Scheduled for release on January 23, 2026							
① Top page, etc.	W250 x H100	fixed	150,000JPY	200,000JPY	※	6	Feb. 20(Fri.), 2026
②Middle Category Page Opening of the Program NEW	Horizontal logo	fixed	50,000JPY	80,000JPY	※	各2	Feb. 20(Fri.), 2026

Mail Magazine(30,000JPY-) ¦ This is an e-mail magazine for speakers and past participants, which can be promoted in text format within the Meeting information distributed from the official JSAP e-mail address.

fee 30,000JPY～150,000JPY

Logo on participation badge

Your logo can be included on the participation ticket for the lecture.

fee 50,000JPY～ (Limited to 3 slots)

lanyard sponsor

Straps will be distributed to participants to use when holding their lecture participation tickets.

fee 50,000JPY+Actual product delivery (up to 7,000 pieces)

Nikkan Kogyo Communications, Inc.
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